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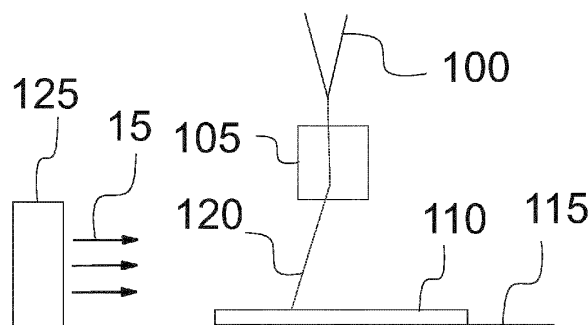
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Fig. 1



(57) Abstract: An apparatus for hole drilling in a substrate is provided. The apparatus includes a laser system configured to apply a laser beam onto the substrate for removing material from a set of areas on the substrate by directing the laser beam onto predefined positions corresponding to the set of areas on the substrate in a sequence. The apparatus includes a ventilation system configured to produce a fluid flow along one or more sides of the substrate. The apparatus controls the laser beam such that the laser beam is sequentially positioned according to a first laser beam movement direction and a second laser beam movement direction.



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